

Kerno Server Product Catalogue

H2 2025

Developed and built in the UAE

Kerno is a premier IT infrastructure manufacturer in UAE

Bringing world-class competencies to build local vendor of enterprise IT equipment to address AI and digitalization initiatives



Research & Development

Products designed and created within Intellectual Property rights owned by local entity

OWN IP & DESIGN



Manufacturing

Manufacturing FAB under construction. Number of manufacturing operations starting from conveyor assembly, testing of equipment, and warehousing

PRODUCED IN UAE



Supply Chain

Procurement team to deliver a worldwide net of hi-tech IT components shipments for FAB manufacturing

IMPORT & EXPORT INCREASE



Services & Maintenance

End-to-end customer support teams to deliver the best client experience with the new UAE enterprise IT equipment - both GCC and worldwide

LOCAL CENTER OF COMPETENCES



KERNO

BY NUMBERS

40



PCB
layers
up to

7000
sqm



4,000 to 10,000
components

100+ skilled
technicians
and engineers



Kerno FAB: Born in UAE. Built for the World.

Kerno established a state-of-the-art microelectronics production facility on 7000 sqm in Dubai Silicon Oasis.

The factory's **sustainable building** is certified at the Platinum level according to the world's most widely used **green building** rating system (LEED)

The production line is engineered to handle the most complex designs, producing **enterprise server-class motherboards** with an astonishing **4,000 to 10,000 components** and up to **40 PCB layers**

The automated **assembly conveyor system** is optimized to deliver **hundreds** of products within just **24 hours**

The factory will employ **100+ skilled technicians and engineers** when running at capacity

Kerno Product Lines

All products are market-ready, and samples can be delivered to the customers for validation

OKAM Universal servers

1



1U and 2U rack servers based on latest Intel and AMD chips suitable for vast majority of enterprise use cases

Access control / Application / DNS server, Hyperconverged environments, Virtualization, Big Data analytics

OKAM Edge servers

2



Maximum GPU and CPU compute packed in short depth 2U chassis

Near edge environments, Smart Factory, Worker safety, Safe City, Traffic analytics, camera-based quality inspection, predictive analytics

UQLEAD AI servers

3



Powerful GPU servers in 2U, 4U, 5U form factor with top of the line PCIe 5.0 and SXM GPUs

Production deployment of ML/AI applications, AI training and inferencing

OTAON Storage systems

4

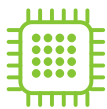


Scalable, fast and simple SAN/NAS storage system based on erasure-coding algorithms

Media archives, cold storage for AI clusters, mixed datacenter workloads, Data Lakes

OKAM Universal servers Accelerate Enterprise and AI Workloads

Kerno's next gen servers help customers take full advantage of new technology with scalable performance using top-speed memory and I/O



More Cores

Better performance with high bandwidth memory (HBM) and up to 4 UPI links to deliver faster workload performance.



Faster Memory

60% faster performance using DDR5 memory to fulfill your workload performance needs.



More Bandwidth

100% faster throughput using PCIe Gen 5 with up to 80 lanes to accommodate different workloads concurrently.



New AI Capabilities

Next Gen Intel® Deep Learning Boost for AI Deep Learning workloads (AMX – INT8 and BFloat16 support / Intel AVX-512). Integration of accelerator features such as DSA*, QAT*, IAX*, and DLB* to improve performance across key workloads.

Datacentre Refresh of Your 3-4 Year Old Servers with Kerno Means

Reclaimed rack space over your 2-3 year old servers

45%

Better price/performance over your existing 3-year old servers

85%

More performance per kW versus previous server generation

25%

40% of servers are over 5 years old, only handle 7% of the work while drawing 66% of the power (Beyond PUE: Tackling IT's Wasted Terawatts, Uptime Institute, January 2020)

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OKAM K01-1210

Rack Server - 1U DP 4-Bay Gen4 NVMe/SATA/SAS
Titanium



Key Features

- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 32 x DIMMs
- Dual ROM Architecture
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 4 x 3.5"/2.5" Gen4 NVMe/SATA/SAS hot-swap bays
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Compatible with SupremeRAID™ by Graid Technology
- 1+1 1600W 80 PLUS Titanium redundant power supplies

Applications

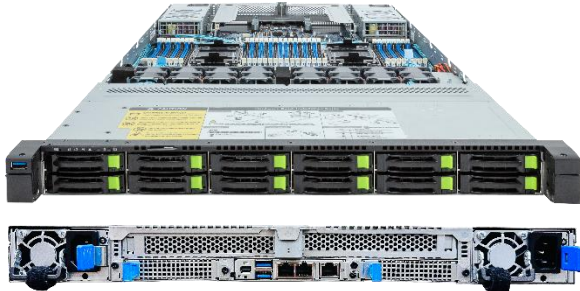
Networks Server, Servers for Hybrid/Private Cloud

Specification	
Dimensions	1U (438 x 43.5 x 815 mm)
CPU	5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor, TDP up to 350W
OS Compatibility	Visit our website for the list of compatible OS
Chipset	Intel® C741
Memory	8-Channel DDR5 RDIMM, 32 x DIMMs [5th Gen Intel Xeon] Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC) [4th Gen Intel Xeon] Up to 4800 MT/s (1DPC), 4400 MT/s (2DPC) [Intel Xeon Max Series] Up to 4800 MT/s (1DPC), 4400 MT/s (2DPC)
LAN	2 x 1Gb/s LAN (1 x Intel I350-AM2), Support NCSI 1 x 10/100/1000 Mbps Management LAN
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP
Storage	Front hot-swap: 4 x 3.5"/2.5" Gen4 NVMe/SATA/SAS -SAS card is required to support SAS drives
RAID	Intel® SATA RAID 0/1/10/5 Onboard VROC key header Optional compatible RAID Cards: NVMe RAID Cards with SupremeRAID™ by Graid Technology Support RAID 0/1/5/6/10
PCIe Expansion Slots	2 x FHHL PCIe Gen5 x16 2 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN
Backplane Board	PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s
TPM	1 x TPM header (SPI), Optional TPM2.0 kit
Power Supply	1+1 1600W 80 PLUS Titanium redundant power supplies AC Input: 100-240V
System Management	ASPEED® AST2600 management controller KERNO Management Console web interface
System Fans	8 x 40x40x56mm (32,000rpm)
Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
Packaging Content	1 x 1U Chassis 1 x Mini-DP to D-Sub cable 1 x 2-Section Rail kit Optional Parts: - 3-Section Rail kit (Supports CMA) - Cable Management Arm

Learn more at: <https://kernoenterprises.com>
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OKAM K01-1210

Rack Server - 1U DP 12-Bay Gen4
NVMe/SATA/SAS Platinum



Key Features

- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 32 x DIMMs
- Dual ROM Architecture
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 12 x 2.5" Gen4 NVMe/SATA/SAS hot-swap bays
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Compatible with SupremeRAID™ by Graid Technology
- Dual 1600W 80 PLUS Platinum redundant power supply

Applications

Networks Server, Servers for Hybrid/Private Cloud

Specification

Dimensions	1U (W438 x H43.5 x D815 mm)	PCIe Expansion Slots	2 x FHHL PCIe Gen5 x16 2 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
CPU	5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor, TDP up to 350W	I/O Ports	Front: 1 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN
OS Compatibility	Visit our website for the list of compatible OS	Backplane Board	PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s
Chipset	Intel® C741	TPM	1 x TPM header (SPI), Optional TPM2.0 kit
Memory	8-Channel DDR5 RDIMM, 32 x DIMMs [5th Gen Intel Xeon] Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC) [4th Gen Intel Xeon] Up to 4800 MT/s (1DPC), 4400 MT/s (2DPC) [Intel Xeon Max Series] Up to 4800 MT/s (1DPC), 4400 MT/s (2DPC) 5600 MT/s support under 2DPC configuration requires verified memory and BIOS setup	Power Supply	Dual 1600W 80 PLUS Platinum redundant power supply AC Input: 100-240V
LAN	2 x 1Gb/s LAN (1 x Intel® I350-AM2), Support NCSI 1 x 10/100/1000 Mbps Management LAN	System Management	ASPEED® AST2600 management controller KERNO Management Console web interface
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP	System Fans	8 x 40x40x56mm
Storage	Front hot-swap: 12 x 2.5" Gen4 NVMe/SATA/SAS -SAS card is required to support SAS drives	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
RAID	Intel® SATA RAID 0/1/10/5 Onboard VROC key header Optional compatible RAID Cards: NVMe RAID Cards with SupremeRAID™ by Graid Technology Support RAID 0/1/5/6/10	Packaging Content	1 x 1U Chassis 1 x Mini-DP to D-Sub cable 1 x 2-Section Rail kit Optional Parts: - 3-Section Rail kit (Supports CMA) - Cable Management Arm

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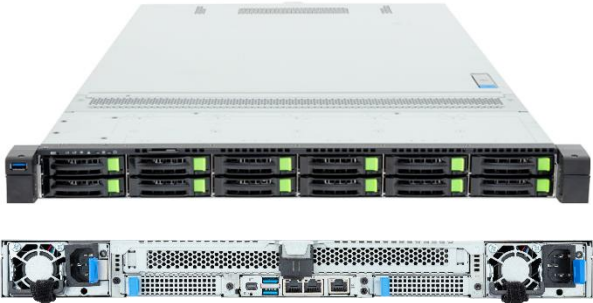
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OKAM K01-12A0

Rack Server - 1U DP 12-Bay Gen5 NVMe/SATA/SAS-4 Titanium



Key Features

- Dual AMD EPYC™ 9005/9004 Series Processors
- 12-Channel DDR5 RDIMM, 24 x DIMMs
- Dual ROM Architecture
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 12 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 3 x M.2 slots with PCIe Gen3 x4 and x2 interface
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 1600W 80 PLUS Titanium redundant power supply

Applications

Networks Server, Servers for Hybrid/Private Cloud

Specification			
Dimensions	1U (W438 x H43.5 x D815 mm)	PCIe Expansion Slots	2 x FHHL PCIe Gen5 x16 2 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
CPU	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Dual processor, cTDP up to 300W - OCP NIC 3.0 ≤ 21W at 30°C ambient, cTDP up to 400W	I/O Ports	Front: 1 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN
OS Compatibility	Visit our website for the list of compatible OS	Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
Chipset	System on Chip	TPM	1 x TPM header (SPI), Optional TPM2.0
Memory	12-Channel DDR5 RDIMM, 24 x DIMMs [EPYC 9005] Up to 6400 MT/s [EPYC 9004] Up to 4800 MT/s	Power Supply	Dual 1600W 80 PLUS Titanium redundant power supply AC Input: 100-240V
LAN	2 x 1Gb/s LAN (1 x Intel® I350-AM2), Support NCSI 1 x 10/100/1000 Mbps Management LAN	System Management	ASPEED® AST2600 Baseboard Management Controller KERNO Management Console web interface
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP	System Fans	8 x 40x40x56mm
Storage	Front hot-swap: 12 x 2.5" Gen5 NVMe/SATA/SAS-4 Internal M.2: 2 x M.2 (2280/22110), PCIe Gen3 x4 1 x M.2 (2280/22110), PCIe Gen3 x2 SAS card is required to support SAS drives	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
RAID	Require RAID add-in cards	Packaging Content	1 x 1U Chassis 1 x Mini-DP to D-Sub cable 1 x 2-Section Rail kit Optional Parts: - 3-Section Rail kit (Supports CMA) - Cable Management Arm

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OKAM K01-12A0

Rack Server - 1U DP 8-Bay Gen5 NVMe/SATA/SAS-4 Platinum



Key Features

- Dual AMD EPYC™ 9004 Series Processors
- 12-Channel DDR5 RDIMM, 24 x DIMMs
- Dual ROM Architecture
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 4 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 4 x 2.5" 9.5mm Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 3 x M.2 slots with PCIe Gen3 x4 and x2 interface
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 1600W 80 PLUS Platinum redundant power supply

Applications

Networks Server, Servers for Hybrid/Private Cloud

Specification	
Dimensions	1U (W438 x H43.5 x D815 mm)
CPU	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Dual processor, cTDP up to 300W -OCP NIC 3.0 ≤ 21W at 30°C ambient, EPYC 9654 cTDP upto 400W *cTDP supported up to 400W under limited thermal conditions
OS Compatibility	Visit our website for the list of compatible OS
Chipset	System on Chip
Memory	12-Channel DDR5 RDIMM 24 x DIMMs Up to 4800 MT/s
LAN	2 x 1Gb/s LAN (1 x Intel® I350-AM2), Support NCSI 1 x 10/100/1000 Mbps Management LAN
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP
Storage	Front hot-swap: 4 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 4 x 2.5" 9.5mm Gen5 NVMe/SATA/SAS-4 Internal M.2: 2 x M.2 (2280/22110), PCIe Gen3 x4 1 x M.2 (2280/22110), PCIe Gen3 x2 SAS card is required to support SAS drives
RAID	Require RAID add-in cards
PCIe Expansion Slots	2 x FHHL PCIe Gen5 x16 2 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
I/O Ports	Front: 1 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN
Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
TPM	1 x TPM header (SPI), Optional TPM2.0
Power Supply	Dual 1600W 80 PLUS Platinum redundant power supply AC Input: 100-240V
System Management	ASPEED® AST2600 Baseboard Management Controller KERNO Management Console web interface
System Fans	8 x 40x40x56mm
Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
Packaging Content	1 x 1U Chassis 1 x Mini-DP to D-Sub cable 1 x 2-Section Rail kit Optional Parts: - 3-Section Rail kit (Supports CMA) - Cable Management Arm

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Specification

Dimensions	1U (W438 x H43.5 x D815 mm)
CPU	Intel® Xeon® 6 Processors - Intel® Xeon® 6700-Series Processors - Intel® Xeon® 6500-Series Processors Dual processors, TDP up to 350W
OS Compatibility	Visit our website for the list of compatible OS
Chipset	System on Chip
Memory	8-Channel DDR5 RDIMM/MRDIMM, 32 x DIMMs [RDIMM] Up to 6400 MT/s (1DPC), 5200 MT/s (2DPC) [MRDIMM] Up to 8000 MT/s MRDIMMs are only supported with Intel® Xeon® 6 Processors with P-cores and in a 1DPC configuration.
LAN	2 x 1Gb/s LAN (1 x Intel® I350-AM2), Support NCSI 1 x 10/100/1000 Mbps Management LAN
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP
Storage	Front hot-swap: 12 x 2.5" Gen5 NVMe/SATA/SAS-4* Internal M.2: 2 x M.2 (2280/22110), PCIe Gen5 x4 1 x M.2 (2280), PCIe Gen5 x2 * Storage card is required to support SATA and SAS drives
RAID	Require RAID add-in cards Onboard VROC key header

Key Features

- Dual Intel® Xeon® 6700/6500-Series Processors
- 8-Channel DDR5 RDIMM / MRDIMM, 32 x DIMMs
- Dual ROM Architecture
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 4 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 3 x M.2 slots with PCIe Gen5 x4 and x2 interface
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- 1+1 1600W 80 PLUS Titanium redundant power supplies

Applications

Networks Server, Servers for Hybrid/Private Cloud

PCIe Expansion Slots	2 x FHHL PCIe Gen5 x16 2 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
I/O Ports	Front: 1 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN
Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
TPM	1 x TPM header (SPI), Optional TPM2.0 1 x PRoT connector (Enabled on demand)
Power Supply	1+1 1600W 80 PLUS Titanium redundant power supplies AC Input: 100-240V
System Management	ASPEED® AST2600 management controller KERNO Management Console web interface
System Fans	8 x 40x40x56mm
Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
Packaging Content	1 x 1U Chassis 1 x Mini-DP to D-Sub cable 1 x 2-Section Rail kit Optional Parts: - 3-Section Rail kit (Supports CMA) - Cable Management Arm

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OKAM K01-1220

Rack Server - 1U DP 12-Bay Gen5 NVMe/SATA/SAS-4



Specification

Dimensions	1U (W438 x H43.5 x D815 mm)
CPU	Intel® Xeon® 6 Processors - Intel® Xeon® 6700-Series Processors - Intel® Xeon® 6500-Series Processors Dual processors, TDP up to 350W
OS Compatibility	Visit our website for the list of compatible OS
Chipset	System on Chip
Memory	8-Channel DDR5 RDIMM/MRDIMM, 32 x DIMMs [RDIMM] Up to 6400 MT/s (1DPC), 5200 MT/s (2DPC) [MRDIMM] Up to 8000 MT/s MRDIMMs are only supported with Intel® Xeon® 6 Processors with P-cores and in a 1DPC configuration.
LAN	2 x 1Gb/s LAN (1 x Intel® I350-AM2), Support NCSI 1 x 10/100/1000 Mbps Management LAN
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP
Storage	Front hot-swap: 12 x 2.5" Gen5 NVMe/SATA/SAS-4* Internal M.2: 2 x M.2 (2280/22110), PCIe Gen5 x4 1 x M.2 (2280), PCIe Gen5 x2 * Storage card is required to support SATA and SAS drives
RAID	Require RAID add-in cards Onboard VROC key header

Key Features

- Dual Intel® Xeon® 6700/6500-Series Processors
- 8-Channel DDR5 RDIMM / MRDIMM, 32 x DIMMs
- Dual ROM Architecture
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 12 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 3 x M.2 slots with PCIe Gen5 x4 and x2 interface
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 1600W 80 PLUS Titanium redundant power supply

Applications

Networks Server, Servers for Hybrid/Private Cloud

PCIe Expansion Slots	2 x FHHL PCIe Gen5 x16 2 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
I/O Ports	Front: 1 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN
Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
TPM	1 x TPM header (SPI), Optional TPM2.0 1 x PRoT connector (Enabled on demand)
Power Supply	Dual 1600W 80 PLUS Titanium redundant power supply AC Input: 100-240V
System Management	ASPEED® AST2600 management controller KERNO Management Console web interface
System Fans	8 x 40x40x56mm
Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
Packaging Content	1 x 1U Chassis 1 x Mini-DP to D-Sub cable 1 x 2-Section Rail kit Optional Parts: - 3-Section Rail kit (Supports CMA) - Cable Management Arm

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OKAM K01-1120

Rack Server - 1U UP 12-Bay Gen5 NVMe/SATA/SAS-4



Key Features

- Single Intel® Xeon® 6700/6500-Series Processors
- 8-Channel DDR5 RDIMM / MRDIMM, 16 x DIMMs
- Dual ROM Architecture
- 1 x 1Gb/s LAN port via Intel® I210-AT
- 12 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 1 x M.2 slot with PCIe Gen5 x2 interface
- 1 x M.2 slot with PCIe Gen5 x2 interface, **shared with SATA**
- 1 x FHHL PCIe Gen5 x16 slot
- 1 x OCP NIC 3.0 PCIe Gen5 x16 slot
- 1+1 1300W 80 PLUS Titanium redundant power supplies

Applications

Networks Server, Servers for Hybrid/Private Cloud

Specification	
Dimensions	1U (W438 x H43.5 x D710 mm)
CPU	Intel® Xeon® 6 Processors - Intel® Xeon® 6700-Series Processors - Intel® Xeon® 6500-Series Processors Dual processors, TDP up to 350W
OS Compatibility	Visit our website for the list of compatible OS
Chipset	System on Chip
Memory	8-Channel DDR5 RDIMM/MRDIMM, 16 x DIMMs [RDIMM] Up to 6400 MT/s (1DPC), 5200 MT/s (2DPC) [MRDIMM] Up to 8000 MT/s MRDIMMs are only supported with Intel® Xeon® 6 Processors with P-cores and in a 1DPC configuration.
LAN	1 x 1Gb/s LAN (1 x Intel® I210-AT), Support NCSI 1 x 10/100/1000 Mbps Management LAN
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP
Storage	Front hot-swap: 12 x 2.5" Gen5 NVMe/SATA/SAS-4 Internal M.2: 1 x M.2 (2280/22110), PCIe Gen5 x2 1 x M.2 (2280/22110), PCIe Gen5 x2, shared with SATA * SAS card is required to support SAS drives To enable the M.2 slot, please adjust the switch according to the manual
RAID	Require RAID add-in cards Onboard VROC key header
PCIe Expansion Slots	1 x FHHL PCIe Gen5 x16 1 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
I/O Ports	Front: 1 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN
Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
TPM	1 x TPM header (SPI), Optional TPM2.0 1 x PrOT connector (Enabled on demand)
Power Supply	1+1 1300W 80 PLUS Titanium redundant power supplies AC Input: 100-240V
System Management	ASPEED® AST2600 management controller KERNO Management Console web interface
System Fans	4 x 40x40x28mm 4 x 40x40x56mm
Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
Packaging Content	1 x 1U Chassis 1 x Mini-DP to D-Sub cable 1 x 2-Section Rail kit Optional Parts: - 3-Section Rail kit (Supports CMA) - Cable Management Arm

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Key Features

- Single Intel® Xeon® 6700/6500-Series Processors
- 8-Channel DDR5 RDIMM / MRDIMM, 16 x DIMMs
- Dual ROM Architecture
- 1 x 1Gb/s LAN port via Intel® I210-AT
- 12 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 1 x M.2 slot with PCIe Gen5 x2 interface
- 1 x M.2 slot with PCIe Gen5 x2 interface, shared with SATA
- 1 x FHHL PCIe Gen5 x16 slot
- 1 x OCP NIC 3.0 PCIe Gen5 x16 slot
- 1+1 1600W 80 PLUS Titanium redundant power supplies

Applications

Specification

Dimensions 2U (W438 x H87.5 x D710 mm)

CPU Intel® Xeon® 6 Processors
- Intel® Xeon® 6700-Series Processors
- Intel® Xeon® 6500-Series Processors
Single processor, TDP up to 350W

OS Compatibility Visit our website for the OS Support List

Socket 1 x LGA 4710 (Socket E2)

Chipset System on Chip

Memory 8-Channel DDR5 RDIMM/MRDIMM, 16 x DIMMs
[RDIMM] Up to 6400 MT/s (1DPC), 5200 MT/s (2DPC) [MRDIMM] Up to 8000 MT/s

-MRDIMMs are only supported with Intel Xeon 6 Processors with P-cores and in a 1DPC configuration

LAN 1 x 1Gb/s LAN (1 x Intel® I210-AT), Support NCSI
1 x 10/100/1000 Mbps Management LAN

Video Integrated in ASPEED AST2600®
- 1 x Mini-DP

Storage Front hot-swap: 12 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 Internal M.2: 1 x M.2 (2280/22110), PCIe Gen5 x2 1 x M.2 (2280/22110), PCIe Gen5 x2, shared with SATA
SAS card is required to support SAS drives

RAID Require RAID add-in cards Onboard VROC key header

Networking, Hybrid/Private Cloud Server

TPM 1 x TPM header (SPI), Optional TPM2.0
1 x PRoT connector (only enabled on demand)

PCIe Expansion Slots 1 x FHHL PCIe Gen5 x16
1 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI

I/O Ports Front:
2 x USB 3.2 Gen1
Rear:
2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN

Backplane Board PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s

Power Supply 1+1 1600W 80 PLUS Titanium redundant power supplies
AC Input: 100-240V

System Management ASPEED® AST2600 Baseboard Management Controller
Kerno Management Console web interface

System Fans 4 x 80x80x38mm

Operating Properties Operating: 10°C to 35°C, 8% to 80% (non-condensing)
Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)

Packaging Content 1 x 2U Chassis
1 x Mini-DP to D-Sub cable
1 x 2-Section Rail kit
Optional Parts:
- 3-Section Rail kit (Supports CMA)
- Cable Management Arm

Learn more at: <https://kernoenterprises.com>

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Kerno OKAM K01-2210

Rack Server - 2U DP 24-Bay NVMe/SATA/SAS



Key Features

- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 32 x DIMMs
- Dual ROM Architecture supported
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 8 x 2.5" Gen4 NVMe hot-swappable bays
- 16 x 2.5" SATA/SAS hot-swappable bays
- 4 x FHHL PCIe Gen5 x16 slots
- 4 x LP PCIe Gen5 x8 slots
- 2 x OCP 3.0 Gen5 x16 slots
- 1+1 2000W 80 PLUS Platinum redundant power supplies

Applications

Networking, Hybrid/Private Cloud Server

Specification

Dimensions	2U (W438 x H87.5 x D815 mm)	TPM	1 x TPM header with SPI interface - Optional TPM2.0
CPU	5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor, TDP up to 350W	Expansion Slots	4 x FHHL PCIe Gen5 x16 slots 4 x LP PCIe Gen5 x8 slots 2 x OCP 3.0 Gen5 x16 slots - Supports NCSI function
OS Compatibility	Windows Server 2019 / 2022 RHEL 8.7 / 8.8 / 8.9 / 8.10 / 9.0 / 9.1 / 9.2 / 9.3 / 9.4 SLES 15 SP4 / SP5 / SP6 Ubuntu 22.04.2 / 22.04.3 / 22.04.4 / 24.04 LTS VMware ESXi 7.0 U3 / 8.0 U1, U2, Update 3 Citrix Hypervisor 8.2 LTSR CU1	I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN Internal: 1 x TPM header, 1 x VROC connector
Socket	2 x LGA 4677 (Socket E)	Backplane Board	Speed and bandwidth: PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s
Chipset	Intel® C741 Chipset	Power Supply	1+1 2000W 80 PLUS Platinum redundant power supplies AC Input: 100-240V
Memory	32 x DIMM slots, 8-Channel DDR5 memory RDIMM up to 96GB supported 3DS RDIMM up to 256GB supported Memory speed: Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC)	System Management	ASPEED® AST2600 management controller KERNO Management Console (AMI MegaRAC SP-X)
LAN	2 x 1Gb/s LAN ports (1 x Intel® I350-AM2) - Supported NCSI 1 x 10/100/1000 management LAN	System Fans	4 x 80x80x38mm (18,300rpm)
Video	ASPEED® AST2600 Integrated 2D Graphic Adapter	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Storage	Front side: 8 x 2.5" Gen4 NVMe hot-swappable bays 16 x 2.5" SATA/SAS hot-swappable bays *SAS card is required for SAS devices support	Packaging Content	1 x 2U Chassis 1 x Mini-DP to D-Sub cable 1 x -Section Rail kit Packaging Dimensions: 1077 x 679 x 300 mm
RAID	Intel® SATA RAID 0/1/10/5		

Learn more at: <https://kernoenterprises.com>

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OKAM K01-2210

Rack Server - 2U DP 2 x PCIe Gen5 GPUs 2400W



Key Features

- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- Supports up to 2 x Dual slot Gen5 GPUs
- 8-Channel DDR5 RDIMM, 32 x DIMMs
- Dual ROM Architecture supported
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 4 x 3.5"/2.5" Gen4 NVMe/SATA/SAS hot-swappable bays
- 8 x 3.5"/2.5" SATA/SAS hot-swappable bays
- 2 x FHFL PCIe Gen5 x16 slots for GPUs
- 2 x FHHL PCIe Gen5 x16 slots
- 4 x LP PCIe Gen5 x8 slots
- 2 x OCP 3.0 Gen5 x16 slots
- Dual 2400W 80 PLUS Platinum redundant power supply

Specification

Dimensions	2U (W438 x H87.5 x D815 mm)	TPM	1 x TPM header with SPI interface - Optional TPM2.0
CPU	5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor, TDP up to 350W	Expansion Slots	2 x FHFL PCIe Gen5 x16 slots for GPUs 2 x FHHL PCIe Gen5 x16 slots 4 x LP PCIe Gen5 x8 slots 2 x OCP 3.0 Gen5 x16 slots - Support NCSI function
OS Compatibility	Windows Server 2019 / 2022 RHEL 8.7 / 8.8 / 8.9 / 8.10 / 9.0 / 9.1 / 9.2 / 9.3 / 9.4 SLES 15 SP4 / SP5 / SP6 Ubuntu 22.04.2 / 22.04.3 / 22.04.4 / 24.04 LTS VMware ESXi 7.0 U3 / 8.0 U1, U2, Update 3 Citrix Hypervisor 8.2 LTSR CU1	I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN Internal: 1 x TPM header, 1 x VROC connector
Socket	2 x LGA 4677 (Socket E)	Backplane Board	Speed and bandwidth: PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s
Chipset	Intel® C741 Chipset	Power Supply	Dual 2400W 80 PLUS Platinum redundant power supply AC Input: 100-240V *The system power supply requires C19 power cord.
Memory	32 x DIMM slots, 8-Channel DDR5 memory RDIMM up to 96GB supported 3DS RDIMM up to 256GB supported Memory speed: Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC)	System Management	ASPEED® AST2600 management controller KERNO Management Console (AMI MegaRAC SP-X)
LAN	2 x 1Gb/s LAN ports (1 x Intel® I350-AM2) - Supported NCSI 1 x 10/100/1000 management LAN	System Fans	4 x 80x80x38mm (18,300rpm)
Video	ASPEED® AST2600 Integrated 2D Graphic Adapter	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Storage	4 x 3.5"/2.5" Gen4 NVMe/SATA/SAS hot-swappable bays 8 x 3.5"/2.5" SATA/SAS hot-swappable bays *SAS card is required for SAS devices support	Packaging Content	1 x 2U Chassis 1 x Mini-DP to D-Sub cable 1 x 2-Section Rail kit Packaging Dimensions: 1077 x 679 x 300 mm
RAID	Intel® SATA RAID 0/1/10/5		

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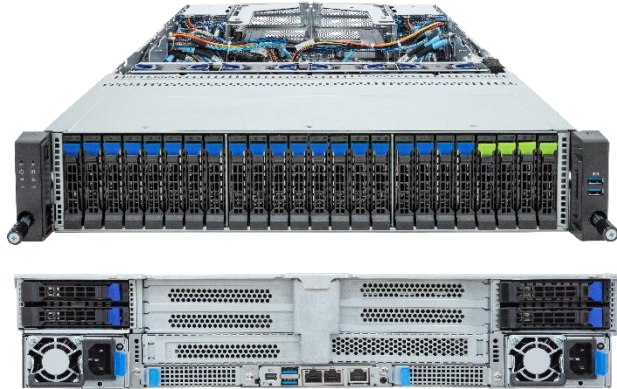
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Kerno OKAM K01-22A0

Rack Server - 2U DP 24+4-Bay
Gen5 NVMe/SATA/SAS-4 with expander Platinum



Key Features

- Dual AMD EPYC™ 9004 Series Processors
- 12-Channel DDR5 RDIMM, 24 x DIMMs
- Dual ROM Architecture
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 4 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 20 x 2.5" SATA/SAS-4 hot-swap bays
- 4 x 2.5" SATA/SAS-4 hot-swap bays on the rear side
- Onboard 24Gb/s SAS-4 expander
- 3 x M.2 slots with PCIe Gen3 x4 and x2 interface
- 4 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- 1+1 2000W 80 PLUS Platinum redundant power supplies

Applications

Networks Server, Servers for Hybrid/Private Cloud

Specification

Dimensions	2U (W438 x H87.5 x D815 mm)
CPU	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Dual processor, cTDP up to 300W - EPYC 9654 cTDP up to 400W
OS Compatibility	OS Support List
Socket	2 x LGA 6096 (Socket SP5)
Chipset	System on Chip
Memory	12-Channel DDR5 RDIMM, 24 x DIMMs Up to 4800 MT/s
LAN	2 x 1Gb/s LAN (1 x Intel® I350-AM2), Support NCSI 1 x 10/100/1000 Mbps Management LAN
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP
Storage	Front hot-swap: 4 x 2.5" Gen5 NVMe/SATA/SAS-4 20 x 2.5" SATA/SAS-4 Rear hot-swap: 4 x 2.5" SATA/SAS-4 Internal M.2: 2 x M.2 (2280/22110), PCIe Gen3 x4 1 x M.2 (2280/22110), PCIe Gen3 x2 Storage card is required to enable SATA and SAS drives. - Broadcom SAS4x48 expander - Bandwidth: SATA 6Gb/s or SAS-4 24Gb/s per port
RAID	Require RAID add-in card

PCIe Expansion Slots	4 x FHHL PCIe Gen5 x16 2 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN
Backplane Board	Front: PCIe Gen5 x4 or SATA6Gb/s or SAS-4 24Gb/s Front: PCIe Gen5 x4 or SATA6Gb/s or SAS-4 24Gb/s Rear: SATA6Gb/s or SAS-4 24Gb/s
TPM	1 x TPM header with SPI interface - Optional TPM2.0
Power Supply	1+1 2000W 80 PLUS Platinum redundant power supplies AC Input: 100-240V
System Management	ASPEED® AST2600 Baseboard Management Controller KERNO Management Console web interface
System Fans	4 x 80x80x38mm
Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
Packaging Content	1 x 2U Chassis 1 x Mini-DP to D-Sub cable 1 x 2-Section Rail kit Optional Parts: Cable Management Arm

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OKAM K01-22A0

Rack Server - 2U DP 12+4-Bay Gen5 NVMe/SATA/SAS-4 2400W



Key Features

- Supports up to 2 x Dual slot Gen5 GPUs
- Dual AMD EPYC™ 9005/9004 Series Processors
- 12-Channel DDR5 RDIMM, 24 x DIMMs
- Dual ROM Architecture
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 8 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 4 x 3.5"/2.5" SATA/SAS-4 hot-swap bays
- 4 x 2.5" SATA/SAS-4 hot-swap bays on the rear side
- 2 x FHFL PCIe Gen5 x16 slots for GPUs
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Compatible with SupremeRAID™ by Graid Technology
- 1+1 2400W 80 PLUS Platinum redundant power supplies

Specification

Dimensions	2U (W438 x H87.5 x D815 mm)	PCIe Expansion Slots	2 x FHFL PCIe Gen5 x16, for GPUs 2 x FHHL PCIe Gen5 x16 2 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
CPU	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Dual processor, cTDP up to 240W -The EPYC 9005 series processors with a cTDP of 240W are supported only under ambient temperatures of 25°C	I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN
OS Compatibility	OS Support List	Backplane Board	Front: PCIe Gen5 x4 or SATA6Gb/s or SAS-4 24Gb/s Rear: SATA6Gb/s or SAS-4 24Gb/s
Socket	2 x LGA 6096 (Socket SP5)	TPM	1 x TPM header with SPI interface - Optional TPM2.0
Chipset	System on Chip	Power Supply	1+1 2400W 80 PLUS Platinum redundant power supplies AC Input: 100-240V *The system power supply requires C19 power cord.
Memory	12-Channel DDR5 RDIMM, 24 x DIMMs [EPYC 9005] Up to 6400 MT/s [EPYC 9004] Up to 4800 MT/s	System Management	ASPEED® AST2600 Baseboard Management Controller KERNO Management Console web interface
LAN	2 x 1Gb/s LAN (1 x Intel® I350-AM2), Support NCSI 1 x 10/100/1000 Mbps Management LAN	System Fans	4 x 80x80x38mm
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP	Operating Properties	Operating: 10°C to 30°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
Storage	Front hot-swap: 8 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 4 x 3.5"/2.5" SATA/SAS-4 Rear hot-swap: 4 x 2.5" SATA/SAS-4 SAS card is required to support SAS drives.	Packaging Content	1 x 2U Chassis 1 x Mini-DP to D-Sub cable 1 x 2-Section Rail kit Optional Parts: Cable Management Arm
RAID	Require RAID add-in cards		

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OKAM K01-2220

Rack Server - 2U DP 2U DP 24+2-Bay NVMe/SATA



Key Features

- Dual Intel® Xeon® 6700/6500-Series Processors
- 8-Channel DDR5 RDIMM / MCR DIMM, 32 x DIMMs
- Dual ROM Architecture
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 24 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 2 x 2.5" SATA/SAS-4 hot-swappable bays on the rear side
- 2 x M.2 slot with PCIe Gen5 x4 interface
- 2 x FHHL Dual-slot PCIe Gen5 x16 slots
- 1 x FHHL Single-slot PCIe Gen5 x16 slot
- 1 x OCP 3.0 Gen5 x16 slot
- 1+1 2000W 80 PLUS Titanium redundant power supplies

Applications

Networks Server, Servers for Hybrid/Private Cloud

Specification

Dimensions	2U (W438 x H87.5 x D815 mm)
CPU	Intel® Xeon® 6 Processors - Intel® Xeon® 6700E-Series Processors - Intel® Xeon® 6700P-Series Processors - Intel® Xeon® 6500P-Series Processors Dual processors, TDP up to 350W
OS Compatibility	Visit our website for the list of compatible OS
Chipset	System on Chip
Memory	8-Channel DDR5 RDIMM/MRDIMM, 32 x DIMMs [RDIMM] Up to 6400 MT/s (1DPC), 5200 MT/s (2DPC) [MRDIMM] Up to 8000 MT/s MRDIMMs are only supported with Intel® Xeon® 6 Processors with P-cores and in a 1DPC configuration
LAN	2 x 1Gb/s LAN ports (1 x Intel® I350-AM2) - supports NCSI function 1 x 10/100/1000 Mbps Management LAN
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP
Storage	Front hot-swap: 24 x 2.5" Gen5 NVMe/SATA/SAS-4 Rear hot-swap: 2 x 2.5" SATA/SAS-4 Internal M.2: 2 x M.2 (2280/22110), PCIe Gen5 x4 Storage card is required to support SATA and SAS drives. SAS card is required to support SAS drives.
RAID	Require RAID add-in cards Onboard VROC key header

PCIe Expansion Slots	2 x FHHL PCIe Gen5 x16, dual-slot 1 x FHHL PCIe Gen5 x16, single-slot 1 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN
TPM	1 x TPM header (SPI), Optional TPM2.0 1 x PROT connector
Backplane Board	Front: PCIe Gen5 x4 or SATA6Gb/s or SAS-4 24Gb/s Front: PCIe Gen5 x4 or SATA6Gb/s or SAS-4 24Gb/s Rear: SATA6Gb/s or SAS-4 24Gb/s
Power Supply	1+1 2000W 80 PLUS Titanium redundant power supplies AC Input: 100-240V
System Management	ASPEED® AST2600 management controller KERNO Management Console (AMI MegaRAC SP-X)
System Fans	4 x 80x80x38mm
Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
Packaging Content	1 x 2U Chassis 1 x Mini-DP to D-Sub cable 1 x 2-Section Rail kit

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OKAM K01-2220

Rack Server - 2U DP 4 x PCIe Gen5 GPUs



Key Features

- Supports 4 x Dual-slot Gen5 GPU cards
- Dual Intel® Xeon® 6700/6500-Series Processors
- 8-Channel DDR5 RDIMM / MRDIMM, 32 x DIMMs
- Dual ROM Architecture
- 12 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 1 x M.2 slot with PCIe Gen5 x4 interface
- 4 x FHFL PCIe Gen5 x16 slots for GPUs
- 1 x FHHL PCIe Gen5 x16 slot
- 1 x OCP NIC 3.0 PCIe Gen5 x16 slot
- Dual 2700W 80 PLUS Titanium redundant power supply

Applications

AI Inference & Training, Visual Computing, High-Performance Computing, Networking, Hybrid/Private Cloud Server

Specification

Dimensions	2U (W438 x H87.5 x D815 mm)	PCIe Expansion Slots	4 x FHFL PCIe Gen5 x16, for GPUs 1 x FHHL PCIe Gen5 x16 1 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
CPU	Intel® Xeon® 6 Processors - Intel® Xeon® 6700E-Series Processors - Intel® Xeon® 6700P-Series Processors - Intel® Xeon® 6500P-Series Processors Dual processors, TDP up to 350W	I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x MLAN
OS Compatibility	Visit our website for the list of compatible OS	Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
Chipset	System on Chip	TPM	1 x TPM header (SPI), Optional TPM2.0 kit: CTM012 1 x PRoT connector (only enabled on RoT SKU)
Memory	8-Channel DDR5 RDIMM/MRDIMM, 32 x DIMMs [RDIMM] Up to 6400 MT/s (1DPC), 5200 MT/s (2DPC) [MRDIMM] Up to 8000 MT/s MRDIMMs are only supported with Intel Xeon 6 Processors with Pcores and in a 1DPC configuration	Power Supply	Dual 2700W 80 PLUS Titanium redundant power supply AC Input: 100-240V *The system power supply requires C19 power cord.
LAN	1 x 10/100/1000 Mbps Management LAN	System Management	ASPEED® AST2600 management controller KERNO Management Console (AMI MegaRAC SP-X)
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP	System Fans	1 x 40x40x28mm 4 x 80x80x56mm
Storage	Front hot-swap: 12 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 Internal M.2: 1 x M.2 (2280/22110), PCIe Gen5 x4 Storage card is required to support SATA and SAS drives.	Operating Properties	Operating: 10°C to 30°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
RAID	Require RAID add-in cards Onboard VROC key header	Packaging Content	1 x 2U Chassis 1 x Mini-DP to D-Sub cable 1 x 2-Section Rail kit

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OKAM Edge product line

Industrial AI Focus



Manufacturing

Industrial / Automotive / F&B / Consumer Goods

- Security management
- Predictive maintenance
- Automated quality inspection
- Asset tracking and management
- Workforce safety and productivity

“Need for speed” – swift reaction to dangerous events with edge processing helps to prevent losses



Energy & Utilities

Extraction / Grids & Pipelines / Refineries
/ Water Systems

- Predictive maintenance and anomaly detection
- Asset tracking and management
- Worker safety
- Improving customer experience at the filling stations

Guaranteed processing regardless of the connectivity helps maintain high operating standards even in remote locations



Government

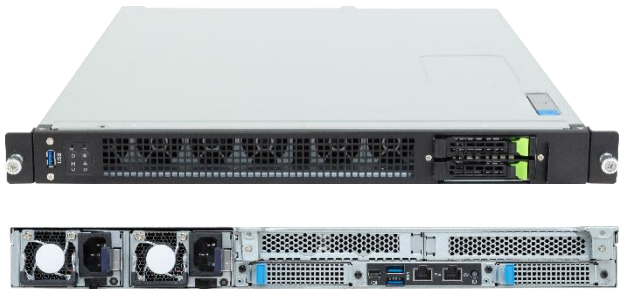
Public Safety / Municipal / Defence / Agencies

- Traffic analytics and management
- Automatic number plate recognition (ANPR)
- Public safety surveillance
- Infrastructure monitoring

Single edge server per building/district lowers complexity, unlike edge PCs hanging on each light pole

OKAM Edge K02-1120

Edge Server - 1U UP 2-Bay Gen5 NVMe/SATA/SAS-4



Key Features

- Single Intel® Xeon® 6700/6500-Series Processors
- 8-Channel DDR5 RDIMM / MRDIMM, 16 x DIMMs
- Dual ROM Architecture
- 1 x 1Gb/s LAN port via Intel® I210-AT
- 2 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 1 x M.2 slot with PCIe Gen5 x2 interface
- 1 x M.2 slot with PCIe Gen5 x2 interface, **shared with SATA**
- 2 x FHFL PCIe Gen5 x16 slots for GPUs
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 800W 80 PLUS Titanium redundant power supply

Applications

Networks Server, Servers for Hybrid/Private Cloud, Edge Server

Specification

Dimensions	1U (W438 x H43.5 x D520 mm)	PCIe Expansion Slots	2 x FHHL PCIe Gen5 x16 2 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
CPU	Intel® Xeon® 6 Processors - Intel® Xeon® 6700-Series Processors - Intel® Xeon® 6500-Series Processors Single processor, TDP up to 350W	I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN
OS Compatibility	Visit our website for the list of compatible OS	TPM	1 x TPM header (SPI), Optional TPM2.0 1 x PRoT connector(enabled on demand)
Chipset	System on Chip	Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
Memory	8-Channel DDR5 RDIMM/MRDIMM, 16 x DIMMs [RDIMM] Up to 6400 MT/s (1DPC), 5200 MT/s (2DPC) [MRDIMM] Up to 8000 MT/s -MRDIMMs are only supported with Intel® Xeon® 6 Processors with P-cores and in a 1DPC configuration	Power Supply	Dual 800W 80 PLUS Titanium redundant power supply AC Input: 100-240V
LAN	1 x 1Gb/s LAN (1 x Intel® I210-AT), Support NCSI 1 x 10/100/1000 Mbps Management LAN	System Management	ASPEED® AST2600 management controller KERNO Management Console (AMI MegaRAC SP-X)
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP	System Fans	5 x 40x40x56mm
Storage	Rear hot-swap: 2 x 2.5" Gen5 NVMe/SATA/SAS-4 Internal M.2: 1 x M.2 (2280/22110), PCIe Gen5 x2 1 x M.2 (2280/22110), PCIe Gen5 x2, shared with SATA -SAS card is required to support SAS drives	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
RAID	Require RAID add-in cards Onboard VROC key header	Packaging Content	1 x 1U Chassis 1 x Mini-DP to D-Sub cable 2-Section Rail kit

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OKAM Edge K02-2120

Edge Server - 2U UP 2 x PCIe Gen5 GPUs



Key Features

- Supports 2 x Dual slot Gen5 GPUs
- Single Intel® Xeon® 6700/6500-Series Processors
- 8-Channel DDR5 RDIMM / MRDIMM, 16 x DIMMs
- Dual ROM Architecture
- 1 x 1Gb/s LAN port via Intel® I210-AT
- 2 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 1 x M.2 slot with PCIe Gen5 x2 interface
- 1 x M.2 slot with PCIe Gen5 x2 interface, **shared with SATA**
- 2 x FHFL PCIe Gen5 x16 slots for GPUs
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- 1+1 2000W 80 PLUS Titanium redundant power supplies

Applications

AI Platform, AI Training Server, AI Inference Server, Visual Computing, Networks Server, Servers for Hybrid/Private Cloud, Edge Server

Specification

Dimensions	2U (W438 x H87.5 x D520 mm)	PCIe Expansion Slots	2 x FHFL PCIe Gen5 x16, for GPUs 2 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
CPU	Intel® Xeon® 6 Processors - Intel® Xeon® 6700-Series Processors - Intel® Xeon® 6500-Series Processors Single processor, TDP up to 350W	I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN
OS Compatibility	Visit our website for the list of compatible OS	TPM	1 x TPM header (SPI), Optional TPM2.0 1 x PRoT connector (enabled on demand)
Chipset	System on Chip	Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
Memory	8-Channel DDR5 RDIMM/MRDIMM, 16 x DIMMs [RDIMM] Up to 6400 MT/s (1DPC), 5200 MT/s (2DPC) [MRDIMM] Up to 8000 MT/s -MRDIMMs are only supported with Intel® Xeon® 6 Processors with P-cores and in a 1DPC configuration	Power Supply	1+1 2000W 80 PLUS Titanium redundant power supplies AC Input: 100-240V
LAN	1 x 1Gb/s LAN (1 x Intel® I210-AT), Support NCSI 1 x 10/100/1000 Mbps Management LAN	System Management	ASPEED® AST2600 Baseboard Management Controller KERNO Management Console web interface
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP	System Fans	4 x 80x80x38mm
Storage	Rear hot-swap: 2 x 2.5" Gen5 NVMe/SATA/SAS-4 Internal M.2: 1 x M.2 (2280/22110), PCIe Gen5 x2 1 x M.2 (2280/22110), PCIe Gen5 x2, shared with SATA -SAS card is required to support SAS drives	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
RAID	Require RAID add-in cards Onboard VROC key header	Packaging Content	1 x 2U Chassis 1 x Mini-DP to D-Sub cable 2-Section Rail kit

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UQLEAD K03-4210

HPC/AI Server - 4U DP NVIDIA OVX™ 8 x GPUs



Features

- Optimized for NVIDIA OVX™ L40S Server with 8 GPUs configuration
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 32 x DIMMs
- Dual ROM Architecture
- 2 x 10Gb/s LAN ports via Intel® X710-AT2
- 12 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 hot-swappable bays
- 1 x M.2 slot with PCIe Gen3 x1 interface
- 8 x FHFL PCIe Gen5 x16 slots for GPUs
- 2 x FHHL PCIe Gen5 x16 slots
- 4 x LP PCIe Gen5 x16 slots
- 1 x LP PCIe Gen4 x16 slot on the front side
- 3+1 3000W 80 PLUS Titanium redundant power supplies

Specification

Dimensions	4U (W448 x H176 x D880 mm)		
CPU	5th/4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor, LGA 4677 (Socket E), TDP up to 350W - NVIDIA OVX Specifications: 2 x Intel® Xeon® Gold 8480	Expansion Slots	8 x PCIe Gen5 x16 FHFL slots for GPUs (with PCIe switches) - NVIDIA OVX Specifications: 8 x NVIDIA L40S 2 x PCIe Gen5 x16 FHHL slots - NVIDIA OVX Specifications: 1 x BlueField-3 (B3220) 4 x PCIe Gen5 x16 low-profile slots - NVIDIA OVX Specifications: 4 x ConnectX-7 1 x PCIe Gen4 x16 low-profile slot
OS Compatibility	Windows Server, Red Hat Enterprise Linux Server, VMware ESXi, SUSE Linux Enterprise, Ubuntu Server, Citrix Hypervisor	I/O Ports	Front: 2 x USB 3.2 Gen1, 1 x VGA, 2 x RJ45, 1 x MLAN Internal: 1 x TPM header, 1 x VROC connector
Chipset	Intel® C741 Chipset	TPM	1 x TPM header with SPI interface (Optional TPM2.0)
Memory	8-Channel DDR5 memory, 32 x DIMM slots RDIMM up to 96GB supported; 3DS RDIMM up to 256GB supported Memory speed: Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC) - NVIDIA OVX Specifications: Min 768GB DDR5 ECC (1 DIMM per slot)	Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
LAN	2 x 10Gb/s LAN ports (1 x Intel® X710-AT2) - Supported NCSI 1 x 10/100/1000 management LAN	Power Supply	3+1 3000W 80 PLUS Titanium redundant power supplies AC Input: 100-240V (The system PSU requires C19 power cord)
Video	ASPEED® AST2600 Integrated 2D Graphic Adapter	System Management	ASPEED® AST2600 Baseboard Management Controller KERNO Management Console (AMI MegaRAC SP-X)
Storage	12 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4* hot-swappable bays *SAS card is required to support SAS drives. - NVIDIA OVX Specifications: 1 x 1TB NVMe Host Boot Drive - NVIDIA OVX Specifications: 2 x 4TB NVMe Host Storage 1 x M.2 slot (M-key, PCIe Gen3 x1, supports 2280/22110)	System Fans	12 x 60x60x38mm (23,000rpm)
RAID	Intel® SATA RAID 0/1/10/5; support optional RAID add-in cards	Operating Properties	Operating temperature: 10°C to 30°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
		Packaging Content	1 x 4U Chassis 1 x Mini-DP to D-Sub cable 1 x L-shape Rail kit Packaging Dimensions: 1200 x 800 x 444 mm w/ pallet

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UQLEAD K03-42A0

HPC/AI Server - 4U DP 8 x PCIe Gen5 GPUs



Key Features

- Supports up to 8 x Dual slot Gen5 GPUs
- Dual AMD EPYC™ 9004 Series Processors
- 12-Channel DDR5 RDIMM, 48 x DIMMs
- Dual ROM Architecture
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 12 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 2 x M.2 slots with PCIe Gen3 x4 interface
- 8 x FHFL PCIe Gen5 x16 slots for GPUs
- 10 x LP PCIe Gen5 x16 slots
- 3+1 3000W 80 PLUS Titanium power supplies

Applications

AI Training, AI Inference, Visual & High-Performance Computing

Specification

Dimensions	4U (W448 x H176 x D880 mm)	Expansion Slots	8 x FHFL PCIe Gen5 x16 slots for GPUs (with PCIe switches) 8 x LP PCIe Gen5 x16 slots on the rear side (with PCIe switches) 2 x LP PCIe Gen5 x16 slots on the front side *The system is validated for use with a single GPU model
CPU	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Dual processor, cTDP up to 400W - At 25°C ambient, cTDP up to 500W	I/O Ports	Front: 2 x USB 3.2 Gen1, 1 x VGA, 2 x RJ45, 1 x MLAN
OS Compatibility	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor	Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
Socket	2 x LGA 6096 (Socket SP5)	Security Modules	1 x TPM header with SPI interface (Optional TPM2.0)
Chipset	System on Chip	Power Supply	3+1 3000W 80 PLUS Titanium redundant power supplies AC Input: 100-240V *The system power supply requires C19 power cord
Memory	12-Channel DDR5 RDIMM, 48 x DIMMs [EPYC 9005] Up to 5200 MT/s (1DPC), 4400 MT/s (1R 2DPC), 4000 MT/s (2R 2DPC) [EPYC 9004] Up to 4800 MT/s (1DPC), 3600 MT/s (2DPC)	System Management	ASPEED® AST2600 Baseboard Management Controller KERNO Management Console web interface
LAN	2 x 1Gb/s LAN (1 x Intel® I350-AM2) - Support NCSI 1 x 10/100/1000 Mbps Management LAN	System Fans	12 x 60x60x38mm (23,000rpm)
Video	Integrated in ASPEED® AST2600 - 1 x VGA port	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8%-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Storage	Front hot-swap: 12 x 2.5" Gen5 NVMe/SATA/SAS-4* *SAS card is required to support SAS drives. Internal M.2: 2 x M.2 (2280/22110), PCIe Gen3 x4	Packaging Content	1 x 4U Chassis 8 x GPU Power cables 1 x L-shape Rail kit
RAID	Require RAID add-in cards		

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UQLEAD K03-42A0

HPC/AI Server - 4U DP NVIDIA HGX™ H200 DLC



Key Features

- Liquid-cooled NVIDIA HGX™ H200
- CPU+GPU direct liquid cooling solution with leak detection
- 900GB/s GPU-to-GPU bandwidth with NVIDIA NVLink™ and NVSwitch™
- Dual AMD EPYC™ 9005/9004 Series Processors
- 12-Channel DDR5 RDIMM, 24 x DIMMs
- Dual ROM Architecture
- Compatible with NVIDIA® BlueField® -3 DPUs and NVIDIAConnectX®-7 NICs
- 2 x 10Gb/s LAN ports via Intel® X710-AT2
- 2 x M.2 slots with PCIe Gen3 x4 and x1 interface
- 8 x 2.5" Gen5 NVMe hot-swap bays
- 4 x FHHL dual-slot PCIe Gen5 x16 slots
- 8 x FHHL single-slot PCIe Gen5 x16 slots
- 4+4 3000W 80 PLUS Titanium redundant power supplies

Applications

AI Platform, AI Training Server, AI Inference Server, High-Performance Computing Server...

Specification			
Dimensions	4U (W447 x H175.5 x D901 mm)	Modular GPU	Liquid-cooled NVIDIA HGX™ H200 with 8 x SXM GPUs
CPU	AMD EPYC™ 9005/9004 Series Processors Dual processor, cTDP up to 500W	PCIe Expansion Slots	4 x FHHL Dual-slot PCIe Gen5 x16 8 x FHHL Single-slot PCIe Gen5 x16
OS Compatibility	Visit our website for the list of compatible OS	I/O Ports	Front: 2 x USB 3.2 Gen1, 1 x VGA, 2 x RJ45, 1 x MLAN Rear: 1 x MLAN
Socket	2 x LGA 6096 (Socket SP5)	TPM	1 x TPM header (SPI), Optional TPM2.0
Chipset	System on Chip	Backplane Board	PCIe Gen5 x4
Memory	12-Channel DDR5 RDIMM, 24 x DIMMs [EPYC 9005] Up to 6400 MT/s [EPYC 9004] Up to 4800 MT/s	Power Supply	4+4 3000W 80 PLUS Titanium power supplies AC Input: 115-240V *The system power supply requires C19 power cord
LAN	Front: 2 x 10Gb/s LAN (1 x Intel® X710-AT2), NCSI 1 x 10/100/1000 Mbps Management LAN Rear: 1 x 10/100/1000 Mbps Management LAN	System Management	ASPEED® AST2600 Baseboard Management Controller KERNO Management Console web interface
Video	Integrated in ASPEED® AST2600 - 1 x VGA port	System Fans	Motherboard: 2 x 60x60x56mm / 2 x 60x60x76mm PCIe slots: 4 x 80x80x56mm GPU tray: 4 x 60x60x38mm
Storage	Front hot-swap: 8 x 2.5" Gen5 NVMe/SATA Internal M.2: 1 x M.2 (2280/22110), PCIe Gen3 x4 1 x M.2 (2280/22110), PCIe Gen3 x1	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
RAID	N/A	Packaging Content	1 x 4U Chassis 1 x L-shape Rail kit

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UQLEAD K03-5210

HPC/AI Server - 5U DP NVIDIA HGX™ H200



Key Features

- NVIDIA HGX™ H200
- 900GB/s GPU-to-GPU bandwidth with NVIDIA NVLink™ and VSwitch™
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 32 x DIMMs
- Dual ROM Architecture
- Compatible with NVIDIA® BlueField®-3 DPUs/SuperNICs
- 2 x 10Gb/s LAN ports via Intel® X710-AT2
- 8 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 4 x FHHL PCIe Gen5 x16 slots
- 8 x LP PCIe Gen5 x16 slots
- 4+2 3000W 80 PLUS Titanium redundant power supplies

Specification

Dimensions	5U (W447 x H219.7 x D945 mm)	Modular GPU	NVIDIA HGX™ H200 with 8 x SXM GPUs
CPU	5 th Generation Intel® Xeon® Scalable Processors 4 th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor, TDP up to 350W	PCIe Expansion Slots	4 x FHHL PCIe Gen5 x16 8 x LP PCIe Gen5 x16
OS Compatibility	Visit our website for the list of compatible OS	I/O Ports	Front: 2 x USB 3.2 Gen1, 1 x VGA, 2 x RJ45, 1 x MLAN Rear: 1 x MLAN
Socket	2 x LGA 4677 (Socket E)	TPM	1 x TPM header (SPI), Optional TPM2.0
Chipset	Intel® C741	Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
Memory	8-Channel DDR5 RDIMM, 32 x DIMMs [5th Gen Intel Xeon] Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC) [4th Gen Intel Xeon] Up to 4800 MT/s (1DPC), 4400 MT/s (2DPC) [Intel Xeon Max Series] Up to 4800 MT/s (1DPC), 4400 MT/s (2DPC)	Power Supply	4+2 3000W 80 PLUS Titanium redundant power supplies AC Input: 115-240V *The system power supply requires C19 power cord
LAN	Front: 2 x 10Gb/s LAN (1 x Intel® X710-AT2), NCSI 1 x 10/100/1000 Mbps Management LAN Rear: 1 x 10/100/1000 Mbps Management LAN	System Management	ASPEED® AST2600 Baseboard Management Controller KERNO Management Console web interface
Video	Integrated in ASPEED® AST2600 - 1 x VGA port	System Fans	Motherboard: 2 x 40x40x28mm / 4 x 60x60x56mm PCIe slots: 4 x 40x40x28mm / 2 x 40x40x56mm GPU tray: 6 x 60x60x76mm / 11 x 80x80x80mm
Storage	Front hot-swap: 8 x 2.5" Gen5 NVMe/SATA/SAS-4 -SAS card is required to support SAS drives	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
RAID	Intel® SATA RAID 0/1/10/5 Support optional RAID add-in cards	Packaging Content	1 x 5U Chassis 1 x L-shape Rail kit

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Kerno Support Options



Local Support 24x7x365

24/7 technical support in English/Arabic with fixed recovery time options up to 4 hours.

ON-GROUND TEAM

Vendor Expertise

Expert level of technical specialists across the entire stack of equipment. Personal approach and dedicated support teams.

DIRECT L3 SUPPORT ACCESS

Center of Excellence

Training center for customers and partners on products of our own development, individual training on request.

VALUED PARTNERSHIP

Test Lab

Own test labs for testing procedures and developing an optimal solution.

INNOVATIVE SOLUTIONS



Classic Tier Programs

	Basic	Optimal	Extended
Self-Service request registration 24x7	✓	✓	✓
Omnichannel support: Call-center, e-mail, self-service portal	✓	✓	✓
Real-time request status monitoring	✓	✓	✓
Spare parts for replacement	✓	✓	✓
Dedicated Service Manager	-	-	✓
Reports	-	2 times a year	quarterly
Updates installation	-	remote	✓
Preventive measures & maintenance	-	2 times a year	quarterly
Root-cause analysis for critical incidents	-	-	✓
Fixed recovery time option	-	-	✓
Remote monitoring	-	-	✓
The incident reaction time (maximum priority)	within 4 hours	within 2 hours	within 1 hour
Support Line Request Resolution	9x5	24x7	24x7

Value-added Options

Customise your support with optional services tailored to your business needs. Options are available for separate purchase and complement the selected support program.

Keep Your Drive

Option to retain defective drives after replacement



Extra Field Service

On-site Engineer Visit for CRU Replacement. KERNO service engineer dispatch to perform Customer Replaceable Unit (CRU) replacement at the equipment installation site.



Spare Parts Reserve

Critical spare parts are reserved locally. List recommended by the KERNO Service Team based on system configuration and risk assessment.



Fixed Delivery Time

Tier support programs. Convenient choice from basic reactive repair to complex support with the allocation of a personified team of service experts



Emergency on-site visit

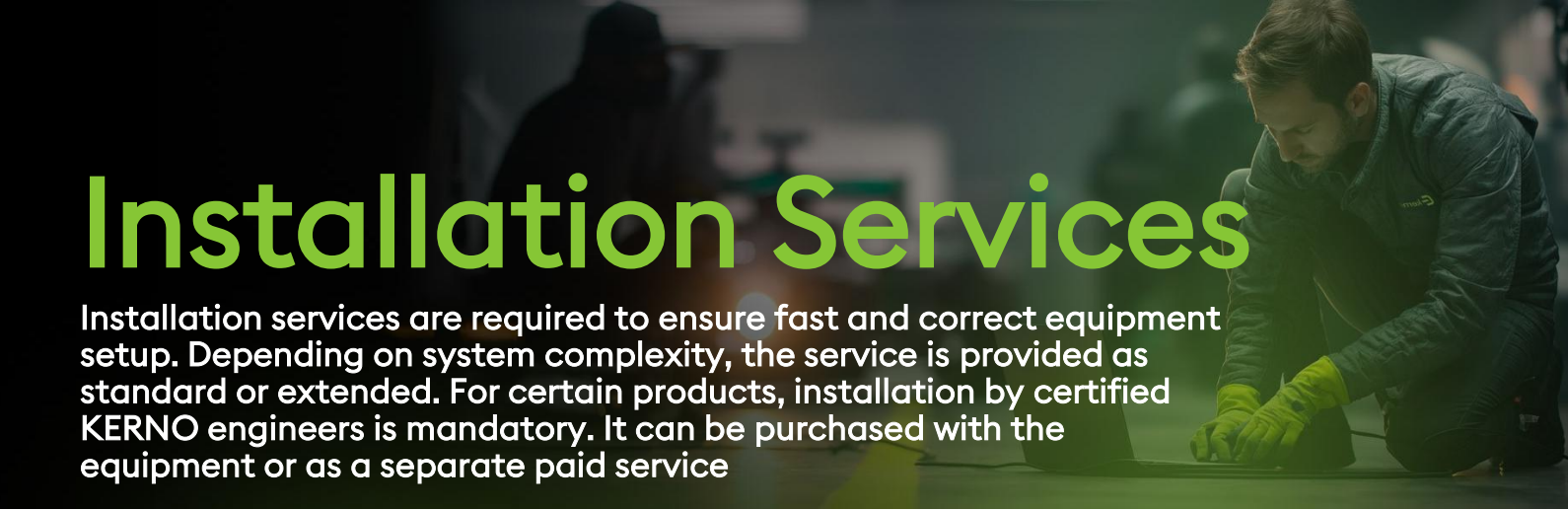
4-Hour On-Site Part Replacement
KERNO service engineer arrives at the installation site with the required part within 4 hours of the replacement approval



Fixed Recovery Time

In case of critical failure, hardware is restored within a guaranteed timeframe: 8, 24, 48, or 72 hours – based on equipment type and service level.





Installation Services

Installation services are required to ensure fast and correct equipment setup. Depending on system complexity, the service is provided as standard or extended. For certain products, installation by certified KERNO engineers is mandatory. It can be purchased with the equipment or as a separate paid service

Standard Installation

- Quick visit by a certified KERNO engineer
- “Installed and ready to use” approach
- Cabling, labeling, initial startup
- Scheduled on weekdays during business hours
- Included by default or available as an add-on

Extended Installation

- Full preparation and technical planning
- Installation + configuration of system software
- Tailored to your IT infrastructure
- Scheduled at your convenience – even nights or holidays
- Available as a paid service

Additional Services

KERNO Customer Service offers additional professional services designed to maximize the reliability and continuity of your critical IT infrastructure.

Installation

Dedicated KERNO specialists deployed at your location to support optimal operation, maintenance, and administration of KERNO products

Express Equipment Check

Fast evaluation of customer-provided diagnostic data to identify critical risks that may significantly impact equipment performance

Preventive on-site Inspections

Proactive measures by KERNO Service specialists to extend the equipment lifecycle through physical and logical level checks, minimizing the risk of unplanned downtime

Equipment Relocation

KERNO Service engineers ensure proper preparation of equipment for relocation and correct commissioning at the new site, securing a smooth and reliable restart



Security and control at every phase of product lifecycle

Local design and manufacturing allows to implement end-to-end threat management as the foundation for a Zero Trust approach

We use the security development lifecycle (SDL) from the time features are conceived and designed, assuring customers that our products are resilient to cyber and physical threats by design

Design

Our supply chain assurance program implements safeguards across the physical, personnel and cyber security to ensure a resilient manufacturing and delivery process

Manufacture

Security controls, automation and comprehensive management tools enable zero trust deployments using robust layers of security across hardware and firmware

Deploy

Security extends all the way to end of life, enabling components and systems to be taken out of production securely by erasing all system data to avoid confidential data compromise and misuse

Service & decommission

Let's define the future together